# 2SD0814A (2SD814A)

## Silicon NPN epitaxial planar type

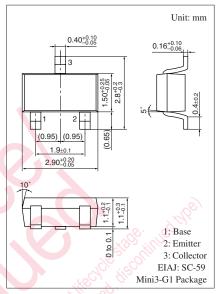
For high breakdown voltage low-frequency and low-noise amplification

#### ■ Features

- High collector-emitter voltage (Base open) V<sub>CEO</sub>
- Low noise voltage NV
- Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing and the magazine packing.

### ■ Absolute Maximum Ratings $T_a = 25$ °C

Parameter	Symbol	Rating	Unit	
Collector-base voltage (Emitter open)	V <sub>CBO</sub>	185	V	
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	185	V	
Emitter-base voltage (Collector open)	$V_{EBO}$	5	V	
Collector current	I <sub>C</sub>	50	mA	
Peak collector current	I <sub>CP</sub>	100	mA	
Collector power dissipation	P <sub>C</sub>	200	mW	
Junction temperature	$T_{j}$	150	°C	
Storage temperature	T <sub>stg</sub>	-55 to +150	°C	



Marking Symbol: L

### ■ Electrical Characteristics $T_a = 25$ °C $\pm 3$ °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-emitter voltage (Base open)	V <sub>CEO</sub>	$I_{\rm C} = 100  \mu \text{A},  I_{\rm B} = 0$				V
Emitter-base voltage (Collector open)	$V_{EBO}$	$I_E = 10 \mu\text{A}, I_C = 0$				V
Collector-base cutoff current (Emitter open)	I <sub>CBO</sub>	$V_{CB} = 100 \text{ V}, I_{E} = 0$			1	μΑ
Forward current transfer ratio *	h <sub>FE</sub>	$V_{CE} = 5 \text{ V}, I_{C} = 10 \text{ mA}$			330	_
Collector-emitter saturation voltage	V <sub>CE(sat)</sub>	$I_C = 30 \text{ mA}, I_B = 3 \text{ mA}$			1	V
Transition frequency	$f_{\mathrm{T}}$	$V_{CB} = 10 \text{ V}, I_{E} = -10 \text{ mA}, f = 200 \text{ MHz}$		150		MHz
Collector output capacitance	$C_{ob}$	$V_{CB} = 10 \text{ V}, I_{E} = 0, f = 1 \text{ MHz}$		2.3		pF
(Common base, input open circuited)						
Noise voltage	NV	$V_{CE} = 10 \text{ V}, I_{C} = 1 \text{ mA}, G_{V} = 80 \text{ dB}$		150		mV
		$R_g = 100 \text{ k}\Omega$ , Function = FLAT				

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

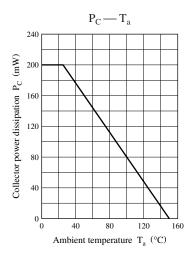
#### 2. \*: Rank classification

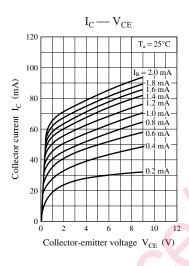
Rank	Q	R	S	
$h_{ m FE}$	90 to 155	130 to 220	185 to 330	

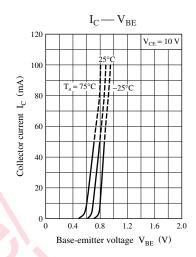
Note) The part number in the parenthesis shows conventional part number.

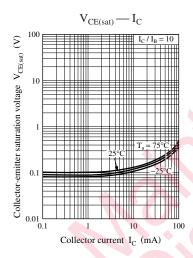
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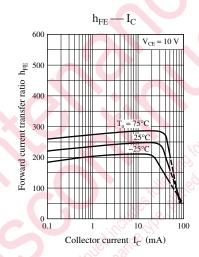
## **Panasonic**

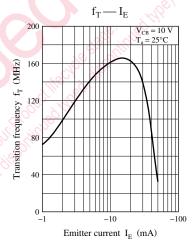


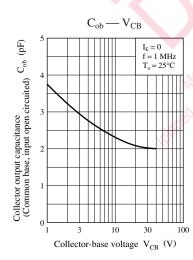












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